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Assistant Commissioner for Patents
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Oct. 26, 2001

Tammy Shyer



GP 2813
#8(me)
1-12-02
MH

Attorney Docket No. 000265

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT
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TECHNOLOGY CENTER 2800

Inventor: L. Richard Carley)
Serial No.: 09/583,386) **Examiner:** Erik Kielin
Filing Date: May 30, 2000) **Art Unit:** 2813

Entitled: MANUFACTURING OF MEMS STRUCTURE IN SEALED CAVITY USING DRY-RELEASE MEMS DEVICE ENCAPSULATION

RESPONSE AND AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

This communication is being filed in response to the Notice of Non-Compliant Amendment dated October 19, 2001 in the above-referenced U.S. patent application.

The Applicant requests the entry of the following Amendments:

In the Specification:

- On page 3, please delete the third full paragraph and replace it with the following paragraph:

Figures 1A and 1B show a top view and a side cross-sectional view respectively of the silicon CMOS wafer used as the base of the MEMS micro-encapsulated structure.

- On page 3, please delete the fourth full paragraph and replace it with the following paragraph:

Figures 2A and 2B show a top view and a cross-sectional view respectively of the wafer of the Figure 1A with a sacrificial layer deposited thereon.

DUPLICATE OF PAPER NO. 7, AMENDMENT B, 1/4/02, EX